SMART DRAM Memory for Networking & Telecom
Reliable, Trusted, Proven

Why DRAM Memory?

SMART's DRAM memory products for networking and telecom applications are built to withstand the extreme environments these settings demand.

They are put through a rigorous test process and can be specifically enhanced for protection from extreme temperatures, moisture, and exposure to severe environmental conditions, making them ideal for telecom field applications.

SMART's memory modules are offered in a variety of form factors and DRAM technologies. SMART provides long-term product support specifically aligned for networking and telecom applications

Special features to support networking applications

- 100% high and low temperature testing
- Component underfill for vibration resistance
- Conformal coating for moisture and environmental protection
- Anti-sulfur passive components for environmental protection

VLP Mini-DIMM

- 8GB, 16GB
- I-temp option
- Very small form factor
- Ideal for NEBS compliance applications

VLP RDIMM

- 8GB to 32GB
- I-temp option
- Ideal for blade applications with height restrictions
- I-temp option

ULP ECC UDIMM

- 8GB to 32GB
- I-temp option
- Ideal for blade applications with height restrictions
- High density with 1-2 DIMM sockets

ECC SO-DIMM

- 8GB to 32GB
- I-temp option
- Ideal for embedded system boards

Contact information

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